Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F0206-07R1** DATE: 4/14/2003
Product Affected: FIFO Products, see attached

Date Effective: 9/17/2002

MEANS OF DISTINGUISHING CHANGED DEVICES:
- ☐ Product Mark
- ☐ Back Mark
- ■ Date Code
- ☐ Other

Contact: Dasharath Patel
Title: Quality Assurance Manager
Phone #: (408) 330-1488
Fax #: (408) 330-1450
E-mail: Dasharath.Patel@idt.com

Attachment:: ■ Yes ☐ No

Samples: Available on request

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ■ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

As a part of IDT's consolidation of wafer fab manufacturing operations, the attached devices are transferred from FAB-2 (Salinas, CA) to FAB-4 (Hillsboro, OR). There will be no change in manufacturing technology. The number "4" added to the stepping character will identify FAB-4 material. Please see attachment for details Starting 9/17/2002, customers will receive material manufactured either at FAB-2 or Fab 4

Addendum: This PCN is being re-issued to include qualification data, and to correct typographical errors in the attachment section of PCN # F0206-07 (original PCN document issued on 06/17/2002). The parts affected and effective date remain unchanged.

RELIABILITY/QUALIFICATION SUMMARY: Please see attachment for qualification summary

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ ☐ ***Approval for shipments prior to effective date.***

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____

Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: F0206-07R1

PCN Type: Wafer Fabrication Site Change

Data Sheet Change: None

Detail of Change: Transfer of manufacturing site for attached devices, from fab-2 (Salinas, CA) to fab-4 (Hillsboro, OR).

Conversion schedule (Estimated)

Samples	Available on request
Production Shipments	9/17/2002

Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: F0206-07R1

Qualification Plan: **QFI-02-05**

Test Vehicle: 7204

Test Description/Condition	Test Methods	SS/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+-I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Qualification Plan: **QFI-02-11**

Test Vehicle: 72V04

Test Description/Condition	Test Methods	SS/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+-I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Characterization Data: Characterization Data is available upon request.

Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: F0206-07R1

Qualification Plan: **QFI-02-09**

Test Vehicle: 72211

Test Description/Condition	Test Methods	SS/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+-I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Qualification Plan: **QFI-02-10**

Test Vehicle: 72V211

Test Description/Condition	Test Methods	SS/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+-I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Characterization Data: Characterization Data is available upon request.

Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: F0206-07R1

Qualification Plan: **QFI-02-03**

Test Vehicle: 72251

Test Description/Condition	Test Methods	SS/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+-I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Qualification Plan: **QFI-02-12**

Test Vehicle: 72V251

Test Description/Condition	Test Methods	SS/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+-I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Characterization Data: Characterization Data is available upon request.

Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: F0206-07R1

Qualification Plan: **QFI-01-19R1**

Test Vehicle: 72245

Test Description/Condition	Test Methods	SS /# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	45/0
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+-I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Characterization Data: Characterization Data is available upon request.

ATTACHMENT - PCN #: F0206-07R1

Device	Date Code Mark Current	Date Code Mark FAB4
IDT7203	**S**yyww	**S4**yyww
IDT7204	**S**yyww	**S4**yyww
IDT7283	**S**yyww	**S4**yyww
IDT7284	**S**yyww	**S4**yyww
IDT72200	**W**yyww	**W4**yyww
IDT72201	**W**yyww	**W4**yyww
IDT72210	**W**yyww	**W4**yyww
IDT72211	**W**yyww	**W4**yyww
IDT72220	**W**yyww	**W4**yyww
IDT72230	**W**yyww	**W4**yyww
IDT72240	**W**yyww	**W4**yyww
IDT72251	**Y**yyww	**Y4**yyww
IDT72420	**W**yyww	**W4**yyww
IDT72421	**W**yyww	**W4**yyww
IDT72801	**W**yyww	**W4**yyww
IDT72811	**W**yyww	**W4**yyww
IDT72851	**Y**yyww	**Y4**yyww

Device	Date Code Mark Current	Date Code Mark FAB4
IDT72V03	**S**yyww	**S4**yyww
IDT72V04	**S**yyww	**S4**yyww
IDT72V83	**S**yyww	**S4**yyww
IDT72V84	**S**yyww	**S4**yyww
IDT72V201	**W**yyww	**W4**yyww
IDT72V211	**W**yyww	**W4**yyww
IDT72V251	**Y**yyww	**Y4**yyww
IDT72V801	**W**yyww	**W4**yyww
IDT72V811	**W**yyww	**W4**yyww
IDT72V851	**Y**yyww	**Y4**yyww

yyww: year/work week